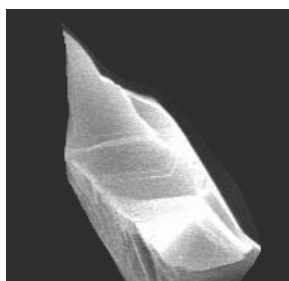


SYNDIA® SYS

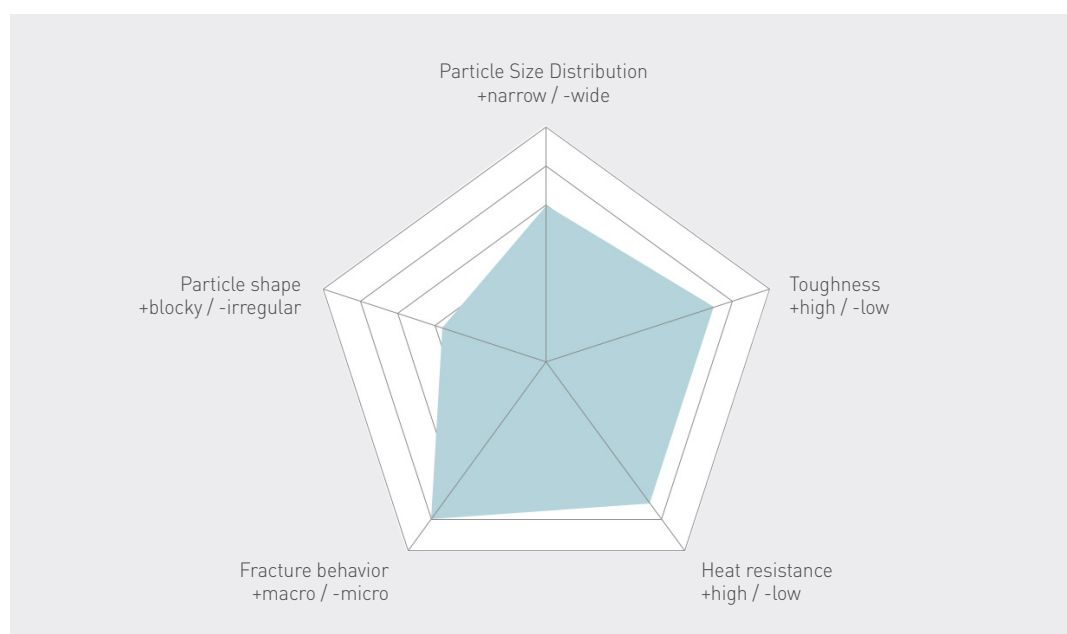
MONOCRYSTALLINE MICRON DIAMOND POWDER



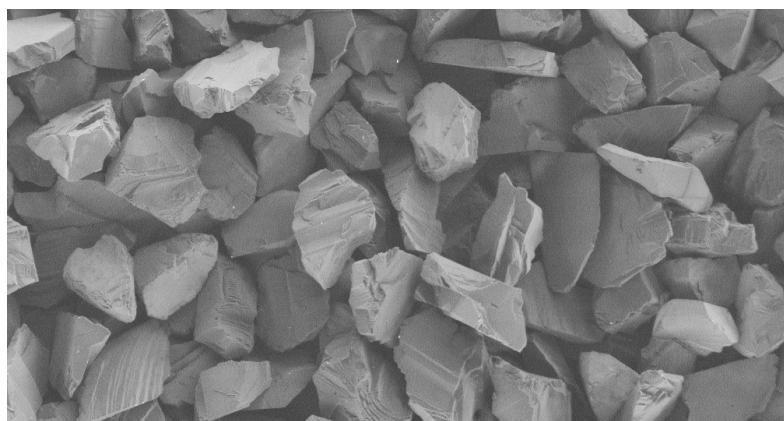
SYNDIA® SYS | HIGH REMOVAL, LOW GRINDING FORCE

SYS has been developed for precision diamond tool makers to offer maximum free cutting ability on various material and application. Its aggressive particles offer the highest removal and the lowest cutting force while maintaining good surface quality through controlled particle shape and size distribution. SYS is suitable for all type of bond systems. Van Moppes guarantees consistent quality by control of raw material, production process and unique inspection method.

PRODUCT CHARACTERIZATION



PROPERTIES	SYP
GRADING	normal
SYNTHESIS	HPHT
CRYSTAL STRUCTURE	monocrystalline
PARTICLE SHAPE	high angularity
FRACTURING MODE	macro-fracture
IMPACT RESISTANCE	medium
PURITY	> 99.9%
BONDING SYSTEMS	PH, PO, VI, MB, EP
DENSITY	3.52 g/cm ³



SYNDIA[®] SYS

MONOCRYSTALLINE MICRON DIAMOND POWDER

MID-POINT	SYS	MESH EQUIVALENT	FEPA EQUIVALENT
41.0	SYS 35-45		
36.0	SYS 30-40	#600	MD40
32.5	SYS 30-40F		
29.0	SYS 22-36	#700	
24.0	SYS 20-30	#800	MD25
19.0	SYS 15-25	#1000	
16.0	SYS 12-22	#1100	MD16
14.0	SYS 10-20	#1200	
12.0	SYS 10-15	#1400	
9.50	SYS 8-12	#1500	MD10
8.00	SYS 6-10	#1800	
6.80	SYS 5.5-8	#2200	
5.70	SYS 4.5-7	#3000	MD6.3
4.80	SYS 4-6	#5000	
4.00	SYS 3-5	#6000	MD64.0
3.30	SYS 2.5-4		
3.00	SYS 2-4	#8000	
2.80	SYS 2.25-3.5		
2.40	SYS 2-3		MD2.5